

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions, and listings, of claims in the application:

Listing of Claims:

1 - 5 (canceled).

6 (previously presented). The high-frequency switching module including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals; and

said filtering circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a second end of said switching circuit, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals,

wherein said plurality of high-frequency terminals are provided on a mounting side surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said high-frequency terminals, the high-frequency terminals spaced by a predetermined distance from the outer edge of the multi-layer assembly.

7 (previously presented). The high-frequency switching module including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals; and

said filtering circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a second end of said switching circuit, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals,

wherein said plurality of high-frequency terminals are provided on a mounting side

surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said high-frequency terminals, said multi-layer assembly having a rectangular four-sided outer shape and having connection terminals provided at corners of the mounting side surface thereof for external connection reinforcement.

8 (canceled).

9 (currently amended) A [[The]] high-frequency switching module including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals; and

said filtering circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a second end of said switching circuit, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency

terminals,

wherein said plurality of high-frequency terminals are provided on a mounting side surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said high-frequency terminals, said multi-layer assembly having a rectangular four-sided outer shape and connection terminals provided at an inner region of the mounting side surface for external connection reinforcement, the connection terminals being positioned at substantially a center of the mounting side surface of the multi-layer assembly.

10 (original). The high-frequency switching module according to claim 9, wherein the connection terminals are positioned in symmetry with respect to substantially the center of the mounting side surface of the multi-layer assembly.

11 - 13 (canceled).

14 (currently amended). A high-frequency switching apparatus module including a switching circuit and a filtering circuit, comprising:  
~~a high-frequency switching module according to claim 1; and~~  
a multi-layer assembly having a plurality of dielectric sheets of layers placed one over another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit being formed with circuit electrodes in the layers of said multi-layer assembly having a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals;

said filtering circuit being formed with circuit electrodes in the layers of said multi-layer assembly having a first end thereof connected to a second end of said switching circuit, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals, wherein said plurality of high-frequency terminals are provided on a mounting side surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said high-frequency terminals; and

a circuit board on which the high-frequency switching module is mounted, wherein lands provided on said circuit board are arranged smaller in size than the high-frequency terminals of said high-frequency switching module.

15 - 18 (canceled).

19 (previously presented). A high-frequency switching module including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals; and

said filtering circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a second end of said switching circuit, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals,

wherein a strip line which forms a part of said switching circuit and/or the filtering circuit is partially located in said multi-layer assembly while the remaining part of the strip line is located on a circuit board on which said multi-layer assembly is mounted, an impedance of the strip line located in the multi-layer assembly being smaller than an impedance of the strip line located on the circuit board, so that a total electric length is not greater than  $\lambda/4$ .

20 (new). A high-frequency switching module including a switching circuit and a filtering circuit, comprising:

a multi-layer assembly having a plurality of dielectric sheets of layers placed one over another;

a plurality of high-frequency terminals provided on outer surfaces of the multi-layer assembly;

said switching circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a first high-frequency terminal of said plurality of high-frequency terminals; and

said filtering circuit formed in the layers of said multi-layer assembly having a first end thereof connected to a second end of said switching circuit, a second end thereof being connected to a second high-frequency terminal of said plurality of high-frequency terminals,

wherein said plurality of high-frequency terminals are provided on a mounting side surface of said multi-layer assembly while lateral sides of said multi-layer assembly are not provided with any electrode for said high-frequency terminals, said multi-layer assembly having a rectangular four-sided outer shape and connection terminals provided at an inner region of the mounting side surface for external connection reinforcement, the connection terminals being positioned in symmetry with respect to substantially a center of the mounting side surface of the multi-layer assembly.